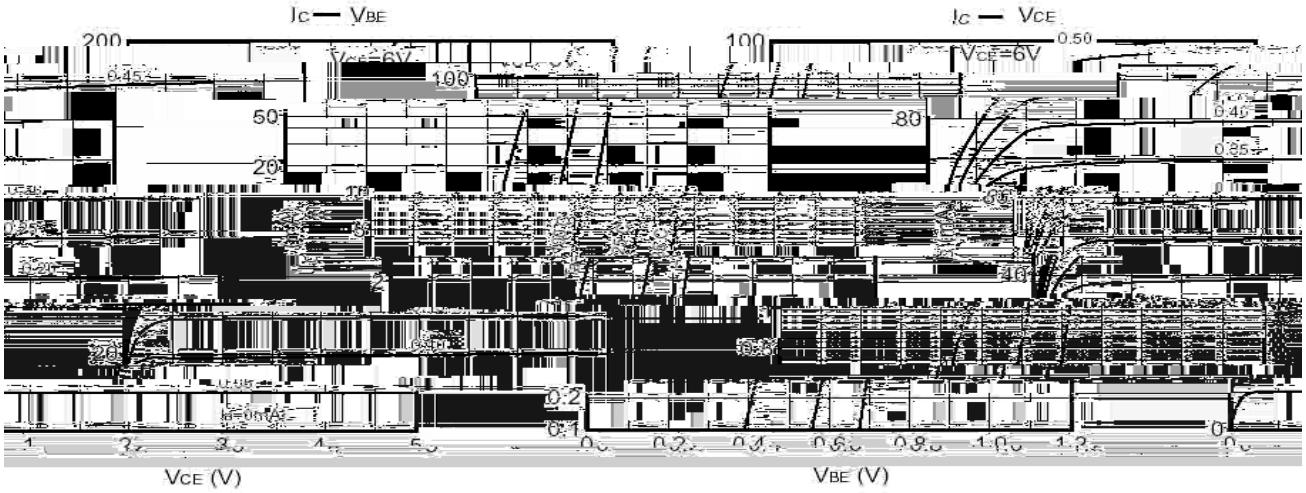
/ Absolute Maximum Ratings(Ta=25)

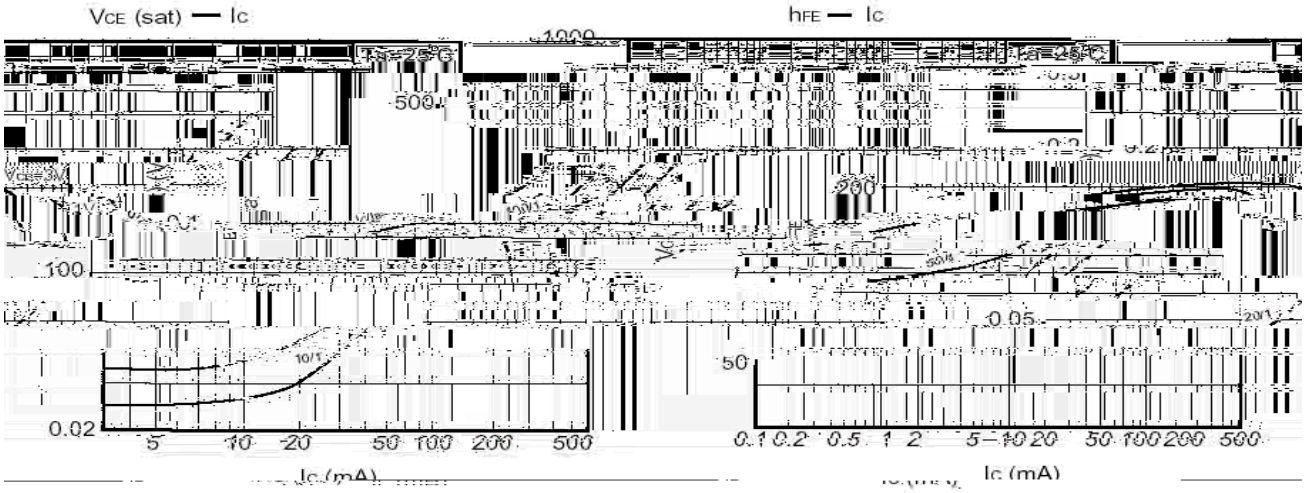
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	50	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current	I_C	0.5	A
Collector Power Dissipation	P_C	0.2	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

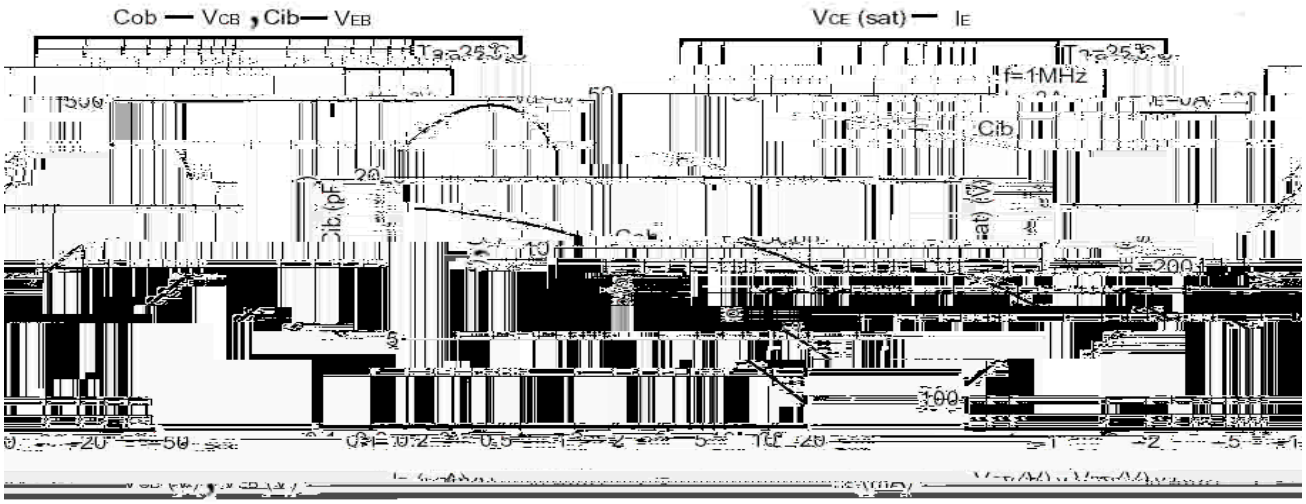
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector-Base Breakdown Voltage	V_{CBO}	I_C=0.1mA I_E=0	50			V
Collector-emitter Breakdown Voltage	V_{CEO}	I_C=1.0mA I_B=0	50			V
Emitter-Base Breakdown Voltage	V_{EBO}	I_E=0.1mA I_C=0	5.0			V
Collector Cut-Off Current	I_{CBO}	V_{CB}=30V I_E=0			0.5	μA
Emitter Base Cut-Off Current	I_{EBO}	V_{EB}=4.0V I_C=0			0.5	μA
DC Current Gain	h_{FE}	V_{CE}=3.0V I_C=0.1A	120		560	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	I_C=150mA I_B=15mA			0.4	V
Transition Frequency	f_T	V_{CE}=5V I_C=20mA f=100MHz		250		MHz
Collector Output Capacitance	C_{ob}	V_{CB}=10V I_E=0 f=1.0MHz		6.5		pF

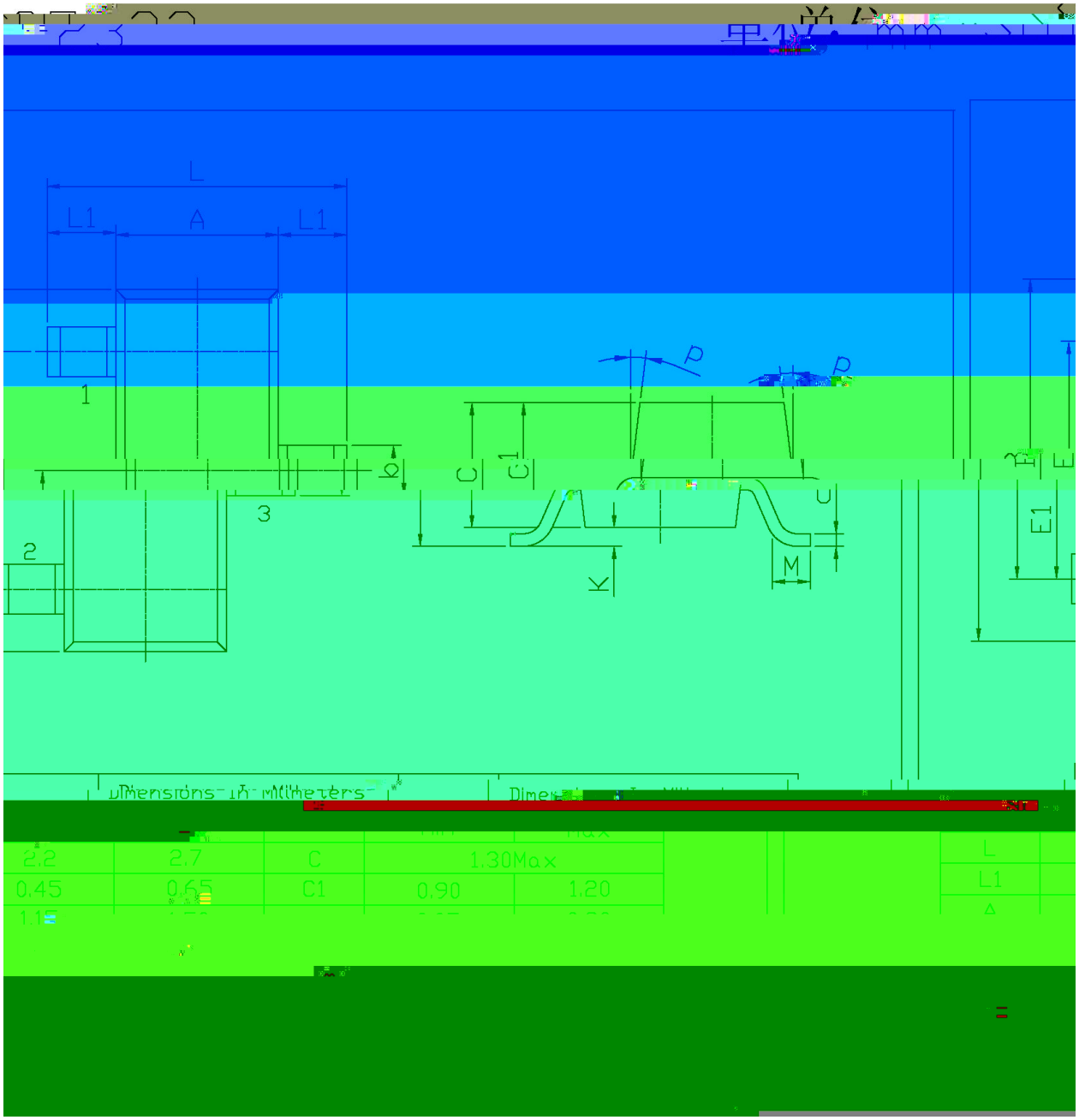
/ Electrical Characteristic Curve



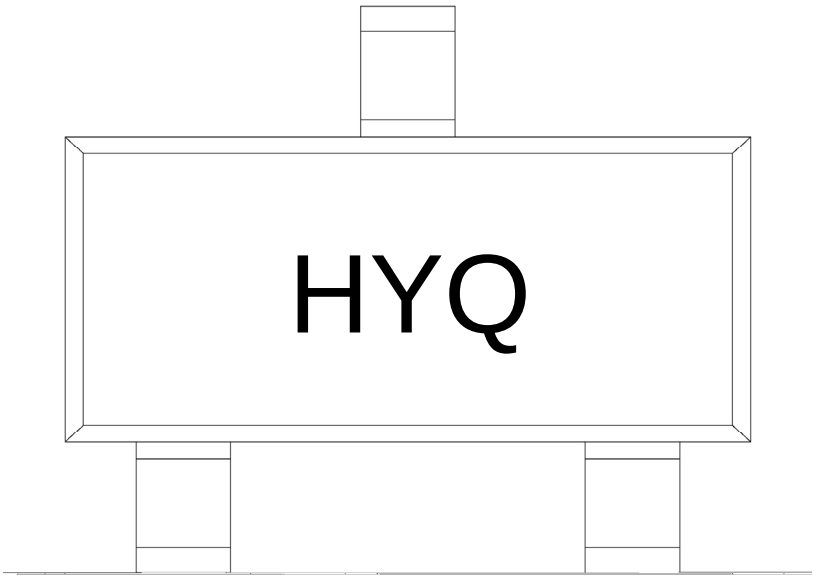




/ Package Dimensions



/ Marking Instructions



H

Y

Q: h_{FE}

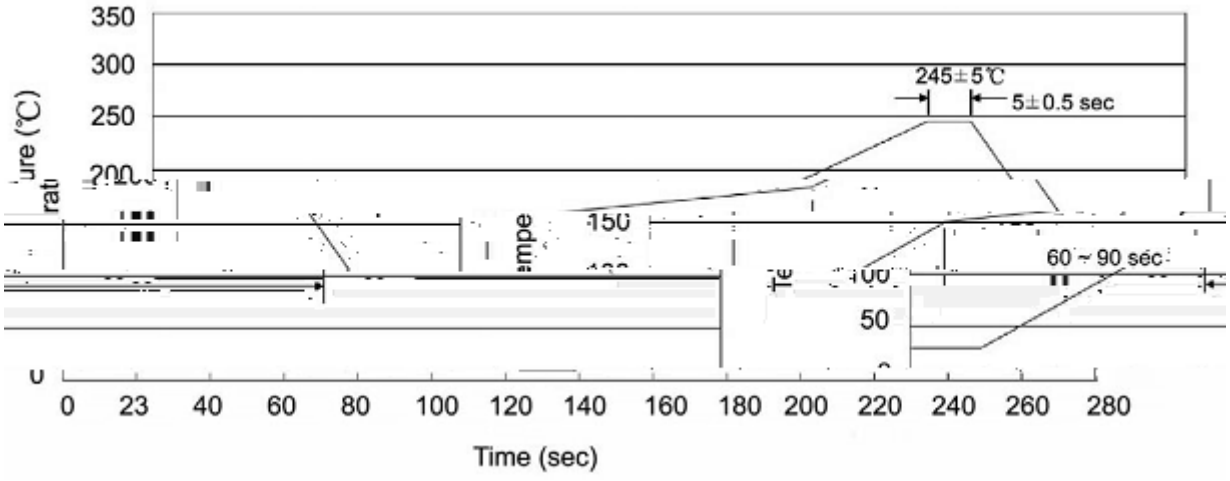
Note:

H: Company Code

Y: Product Type Code

Q: h_{FE} Classifications Symbol Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1 25 150 60 90sec;

1.Preheating:25~150 , Time:60~90sec.

2 245±5 5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3 2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7 ρ ×8	180×120×180	390×385×205

/ Notices